22 March 1965

MEMORANDUM FOR THE RECORD

SUBJECT: Trip Report -- ███████████████████   25X1A
          15, 16, and 17 March 1965

25X1A   The trip was made to ascertain progress on the Chip Processor, under
          contract to ████████████ and to discuss the Sepratron Processor, a new
          processing innovation proposed by ██████████████████████ and presented   25X1A
          to the TDB on 3 March 1965.

              The Chip Processor, due for delivery by 31 March 1965, is progressing
          satisfactorily. However, two requirements levied by the technical represen-
          tative will probably delay delivery to 30 April 1965 or 15 May 1965. These
          requirements are: (a) increasing the size of the chip magazines from a
          16 mount holder size to 36 mount holders, and (b) redesign of the method
          of initial immersion of the film chip into the developer solution. This
          was designed as slow input which would result in the processed chip being
          darker on the bottom due to that portion of the chip being in the developer
          for a longer time than the top of the chip. The contractor was asked to
          design a method of dropping the chip (in the chip mount) into the developer
          solution so that initial developing action is uniform over the entire chip.
          These actions will probably result in a request from the contractor for
          some additional funding as well as the time extension.

              Of special interest is that ████████████ is also designing the   25X1A
          largest color processor (for original film) that has been built. Physically,
          this processor will be nearly 50 feet long by approximately 8 feet wide by
          12 feet high. All transport will be by liquid-air bearings so that the film
          will not be touched from supply to take-up. Additionally, pumps, air and
          chemical mix will take-up nearly as much space as the processor itself.
          This effort, an extremely sensitive one, is being designed for SAC as the   25X1A
          eventual recipient. ████████████████████████ is the prime   25X1A
          contractor on the overall effort, and ██████████████ is the probable   25X1A
          contracting office.

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                                        Development Branch,   P&DS

Declass Review by NIMA/DOD